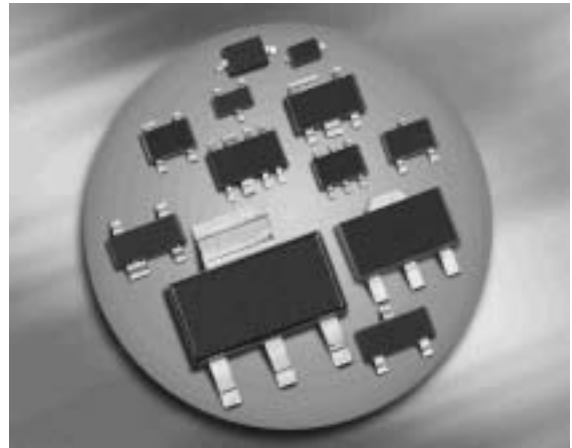
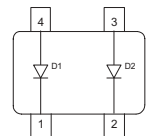
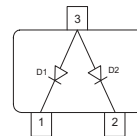
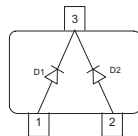
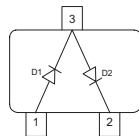
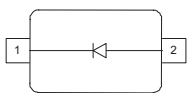


Silicon PIN Diode

- High voltage current controlled RF resistor for RF attenuator and switches
- Frequency range above 1 MHz up to 6 GHz
- Very low capacitance at zero volt reverse bias at frequencies above 1 GHz (typ. 0.17 pF)
- Low forward resistance (typ. 2.1 Ω @ 10 mA)
- Very low signal distortion


BAR64-02L
BAR64-02LRH
BAR64-02V
BAR64-03W
BAR64-04
BAR64-04W
BAR64-05
BAR64-05W
BAR64-06
BAR64-06W
BAR64-07


Type	Package	Configuration	L_S (nH)	Marking
BAR64-02L	TSLP-2-1	single, leadless	0.4	MM
BAR64-02LRH*	TSLP-2-7	single, leadless	0.4	O
BAR64-02V	SC79	single	0.6	O
BAR64-03W	SOD323	single	1.8	2 blue
BAR64-04	SOT23	series	1.8	PPs
BAR64-04W	SOT323	series	1.4	PPs
BAR64-05	SOT23	common cathode	1.8	PRs
BAR64-05W	SOT323	common cathode	1.4	PRs
BAR64-06	SOT23	common anode	1.8	PSs
BAR64-06W	SOD323	common anode	1.4	PSs
BAR64-07	SOT143	parallel pair	2	PTs

* Preliminary Data

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	150	V
Forward current	I_F	100	mA
Total power dissipation BAR64-02L, BAR64-02LRH, $T_S \leq 135^\circ\text{C}$ BAR64-02V, $T_S \leq 125^\circ\text{C}$ BAR64-03W, BAR64-07, $T_S \leq 25^\circ\text{C}$ BAR64-04, -05, -06, $T_S \leq 65^\circ\text{C}$ BAR64-04W, -05W, -06W, $T_S \leq 115^\circ\text{C}$	P_{tot}	250 250 250 250 250	mW
Junction temperature	T_j	150	°C
Operating temperature range	T_{op}	-55 ... 125	
Storage temperature	T_{stg}	-55 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾ BAR64-02L, BAR64-02LRH BAR64-02V, -04W, -05W, -06W BAR64-03W BAR64-04, -05, -06 BAR64-07	R_{thJS}	≤ 60 ≤ 140 ≤ 370 ≤ 340 ≤ 290	

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Breakdown voltage $I_{(\text{BR})} = 5 \mu\text{A}$	$V_{(\text{BR})}$	150	-	-	V
Forward voltage $I_F = 50 \text{ mA}$	V_F	-	-	1.1	

¹For calculation of R_{thJA} please refer to Application Note Thermal Resistance

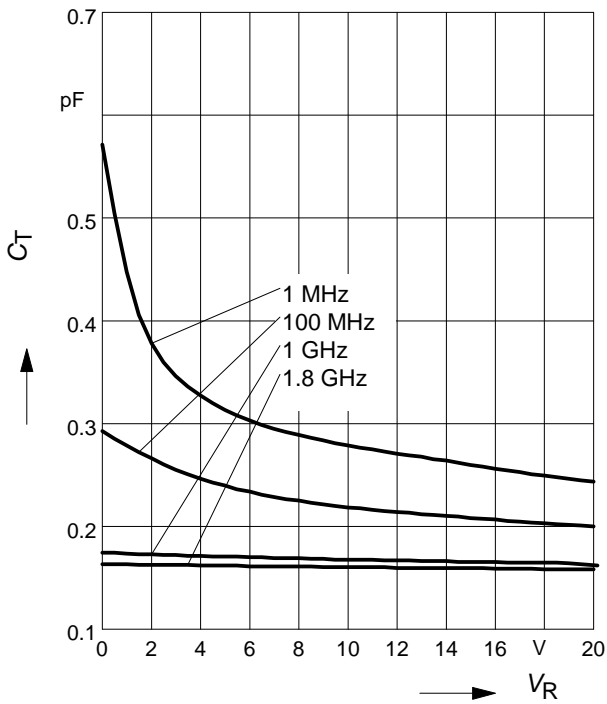
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics					
Diode capacitance $V_R = 20\text{ V}, f = 1\text{ MHz}$ $V_R = 0\text{ V}, f = 100\text{ MHz}$ $V_R = 0\text{ V}, f = 1\dots 1.8\text{ GHz}, \text{BAR64-02L/ -02LRH}$ $V_R = 0\text{ V}, f = 1\dots 1.8\text{ GHz}, \text{all other}$	C_T	-	0.23	0.35	pF
Reverse parallel resistance $V_R = 0\text{ V}, f = 100\text{ MHz}$ $V_R = 0\text{ V}, f = 1\text{ GHz}$ $V_R = 0\text{ V}, f = 1.8\text{ GHz}$	R_P	-	10	-	k Ω
Forward resistance $I_F = 1\text{ mA}, f = 100\text{ MHz}$ $I_F = 10\text{ mA}, f = 100\text{ MHz}$ $I_F = 100\text{ mA}, f = 100\text{ MHz}$	r_f	-	12.5	20	Ω
Charge carrier life time $I_F = 10\text{ mA}, I_R = 6\text{ mA}, \text{measured at } I_R = 3\text{ mA}, R_L = 100\ \Omega$	τ_{rr}	-	1550	-	ns
I-region width	W_I	-	50	-	μm
Insertion loss ¹⁾ $I_F = 3\text{ mA}, f = 1.8\text{ GHz}$ $I_F = 5\text{ mA}, f = 1.8\text{ GHz}$ $I_F = 10\text{ mA}, f = 1.8\text{ GHz}$	$ S_{21} ^2$	-	-0.32	-	dB
Isolation ¹⁾ $V_R = 0\text{ V}, f = 0.9\text{ GHz}$ $V_R = 0\text{ V}, f = 1.8\text{ GHz}$ $V_R = 0\text{ V}, f = 2.45\text{ GHz}$ $V_R = 0\text{ V}, f = 5.6\text{ GHz}$	$ S_{21} ^2$	-	-22	-	

¹BAR64-02L in series configuration, $Z = 50\ \Omega$

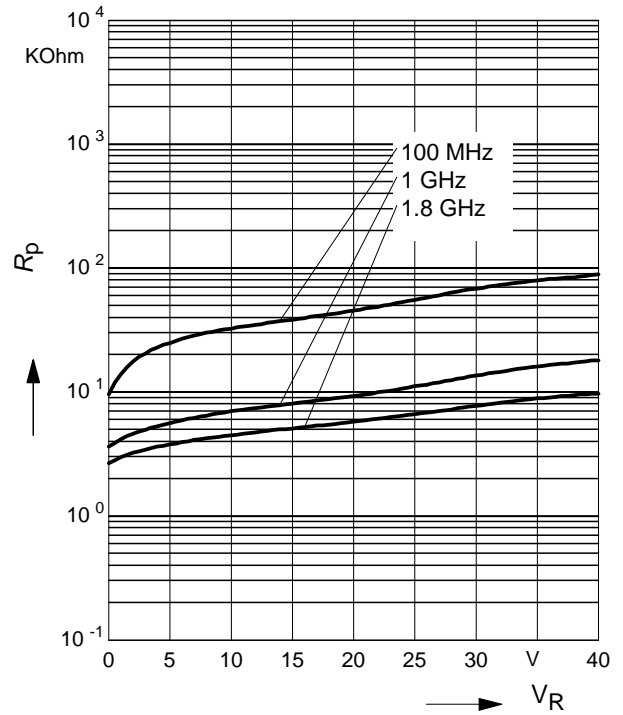
Diode capacitance $C_T = f(V_R)$

$f = \text{Parameter}$



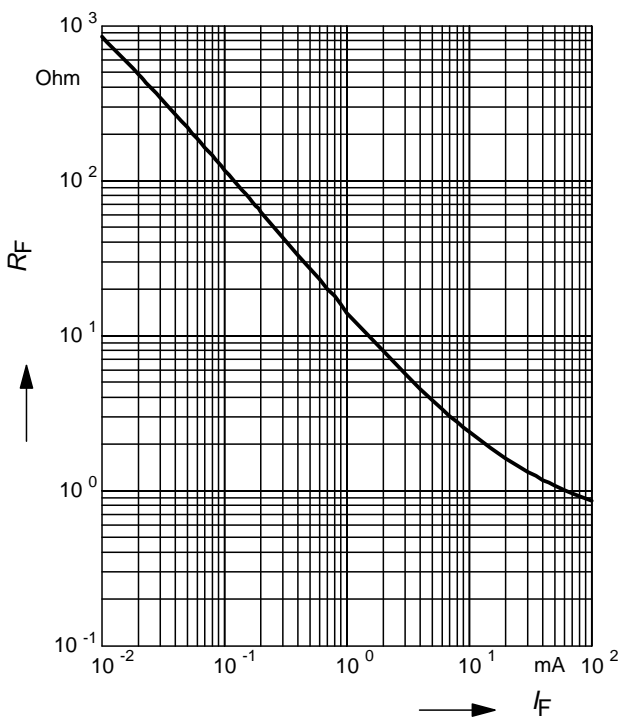
Reverse parallel resistance $R_p = f(V_R)$

$f = \text{Parameter}$



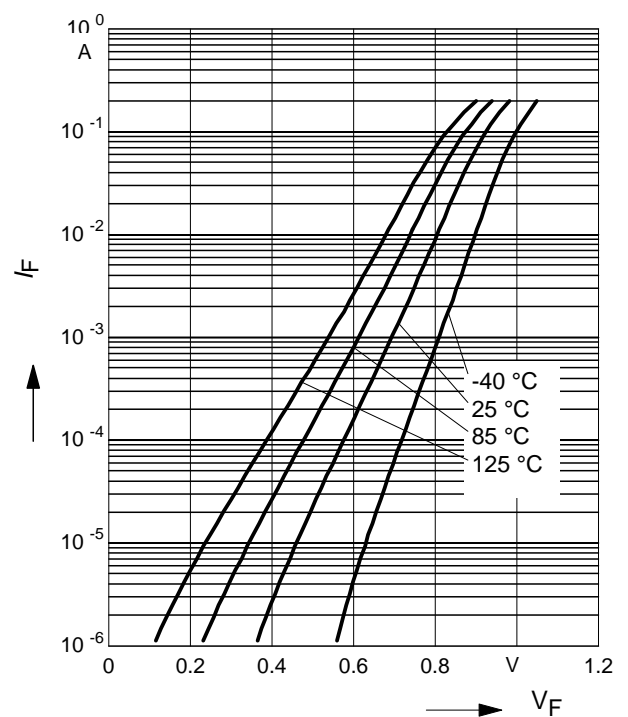
Forward resistance $r_f = f(I_F)$

$f = 100\text{MHz}$



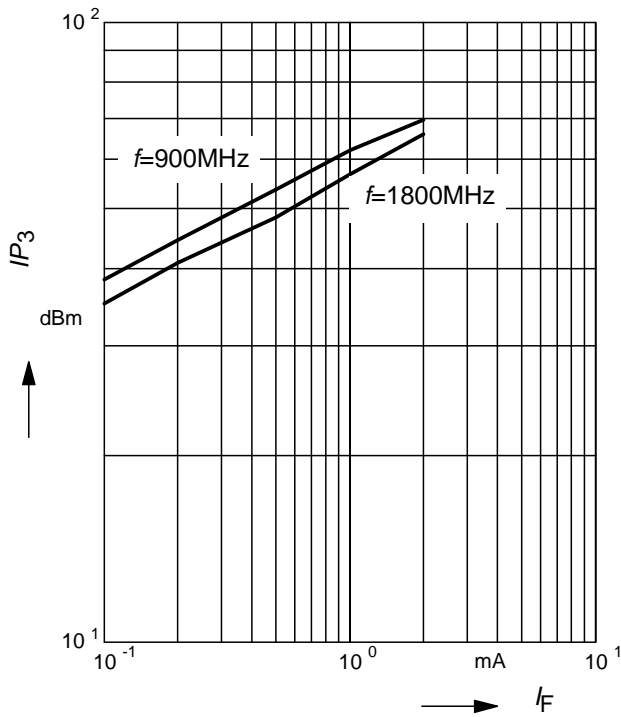
Forward current $I_F = f(V_F)$

$T_A = \text{Parameter}$



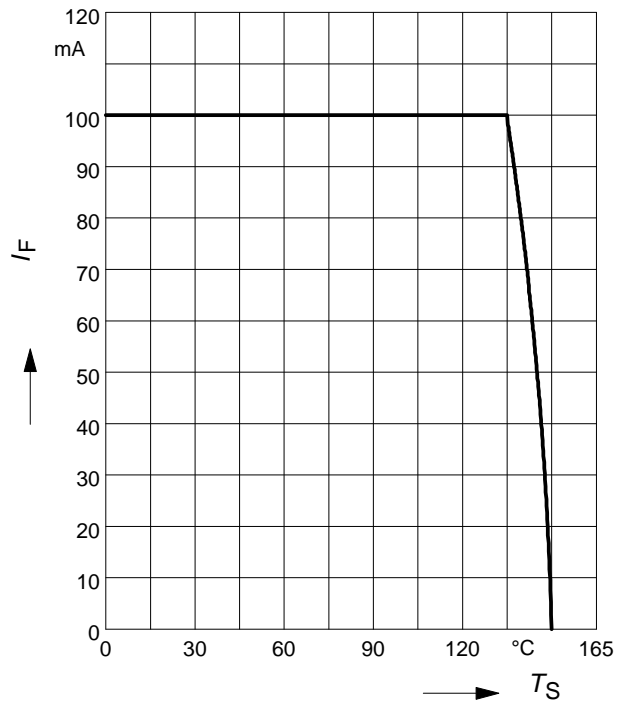
Intermodulation intercept point

$IP_3 = f(I_F); f = \text{Parameter}$



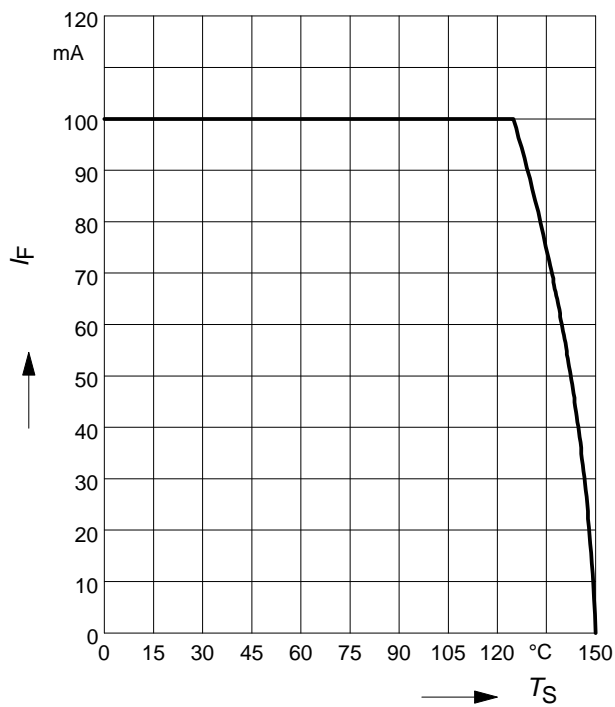
Forward current $I_F = f(T_S)$

BAR64-02L, BAR64-02LRH



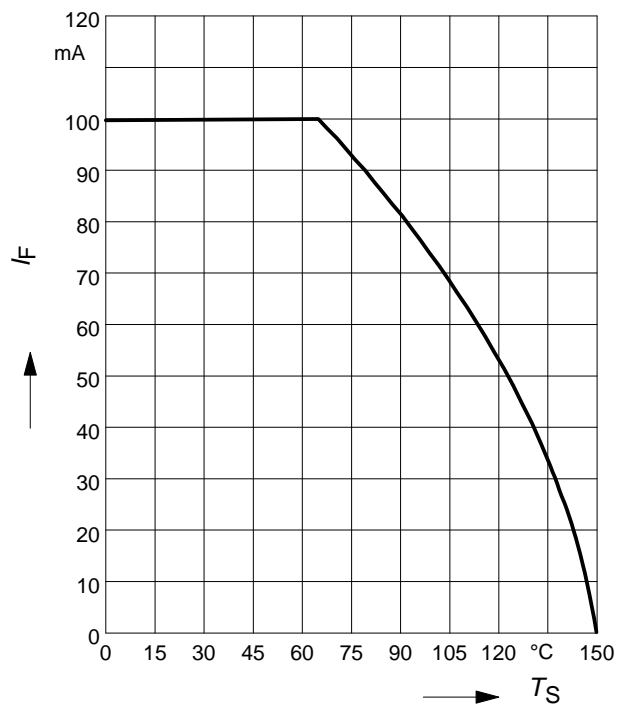
Forward current $I_F = f(T_S)$

BAR64-02V



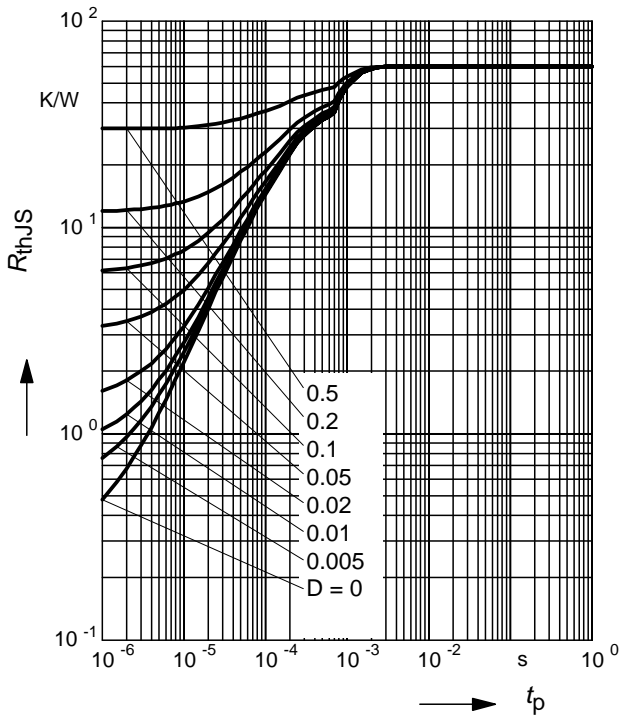
Forward current $I_F = f(T_S)$

BAR64-04, BAR64-06



Permissible Puls Load $R_{thJS} = f(t_p)$

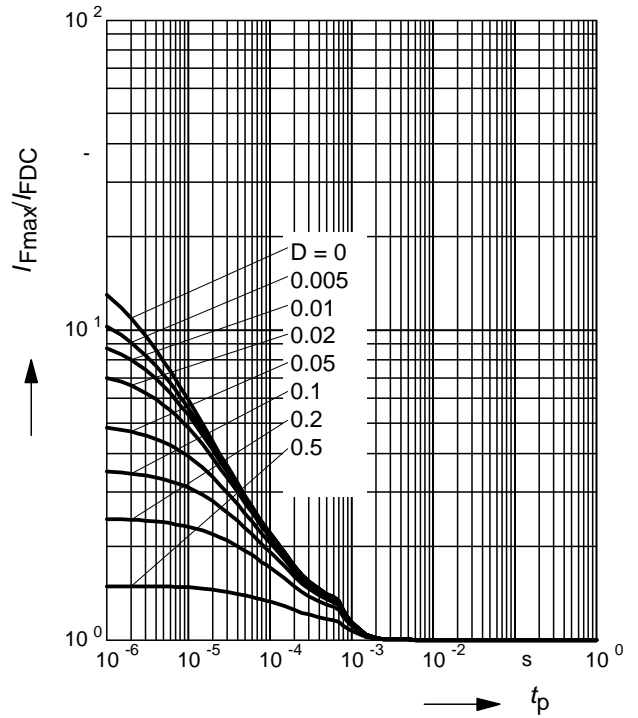
BAR64-02L, BAR64-02LRH



Permissible Pulse Load

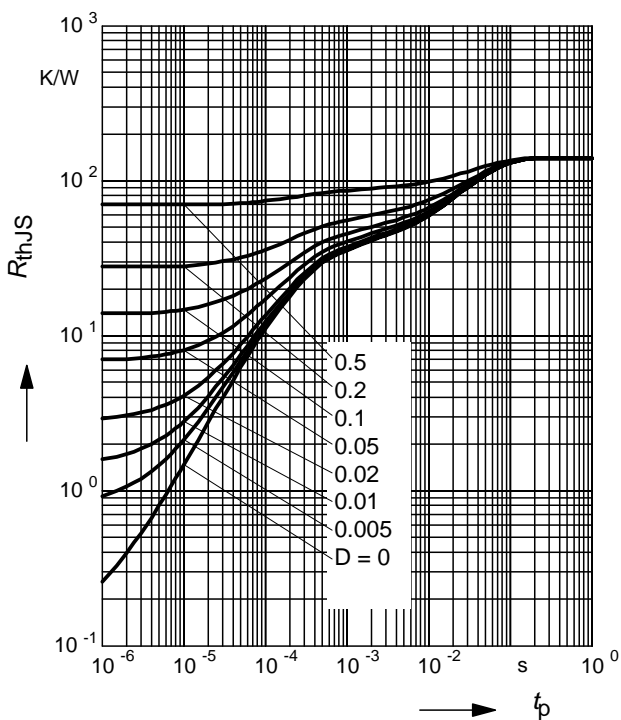
$I_{Fmax} / I_{FDC} = f(t_p)$

BAR64-02L, BAR64-02LRH



Permissible Puls Load $R_{thJS} = f(t_p)$

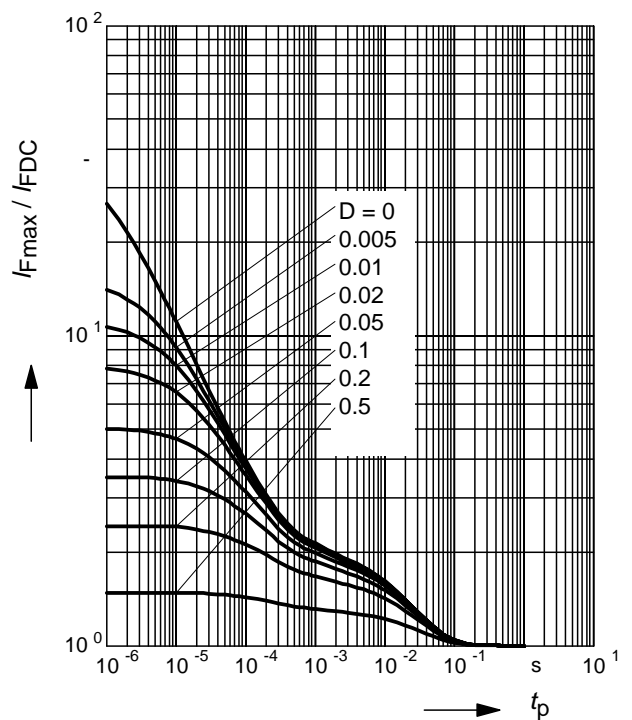
BAR64-02V



Permissible Pulse Load

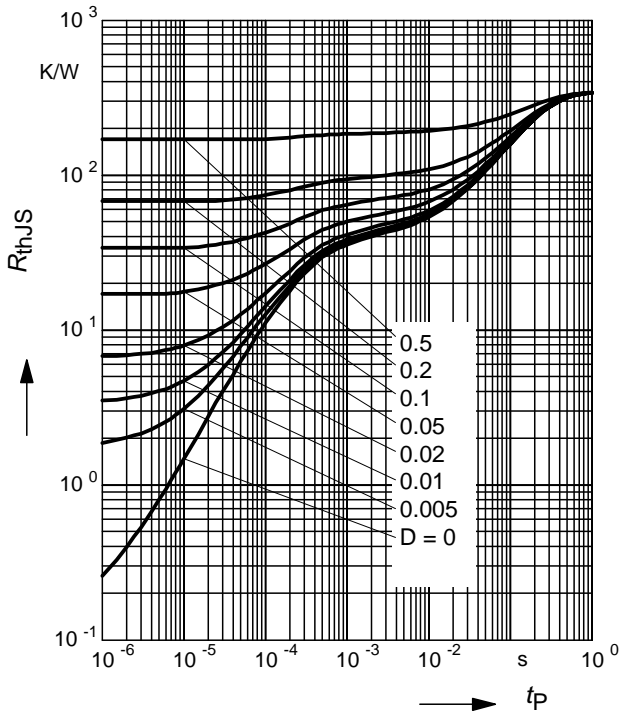
$I_{Fmax} / I_{FDC} = f(t_p)$

BAR64-02V



Permissible Puls Load $R_{thJS} = f(t_p)$

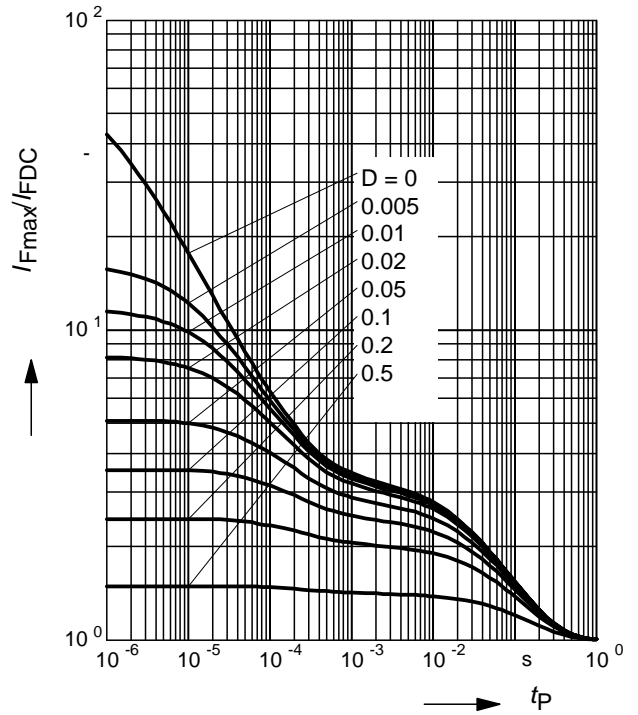
BAR64-04, BAR64-06



Permissible Pulse Load

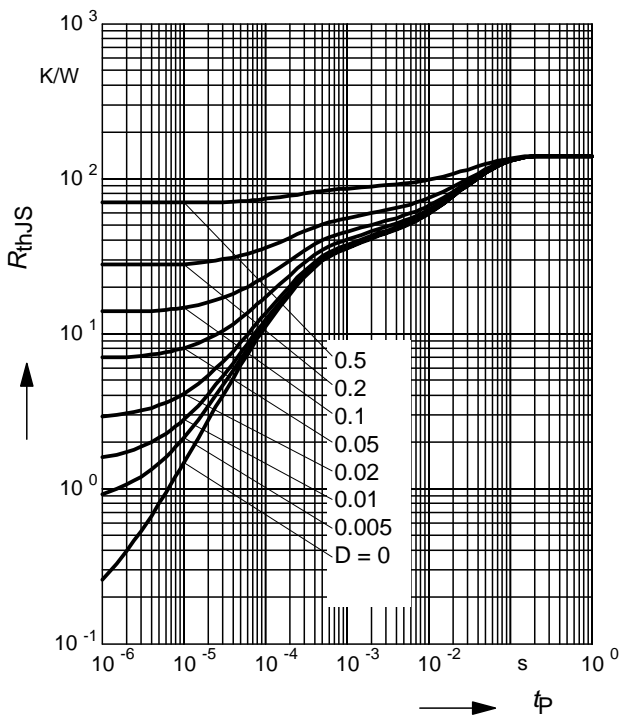
$I_{Fmax} / I_{FDC} = f(t_p)$

BAR64-04, BAR64-06



Permissible Puls Load $R_{thJS} = f(t_p)$

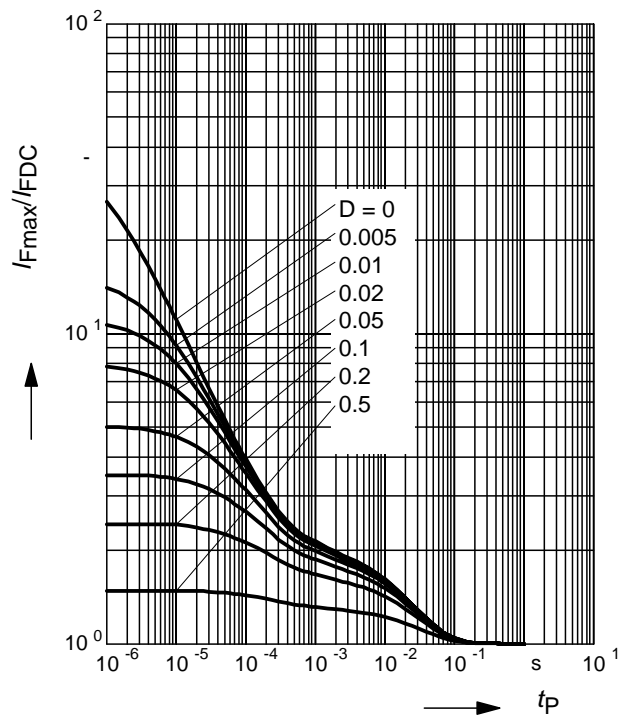
BAR64-04W, BAR64-06W



Permissible Pulse Load

$I_{Fmax} / I_{FDC} = f(t_p)$

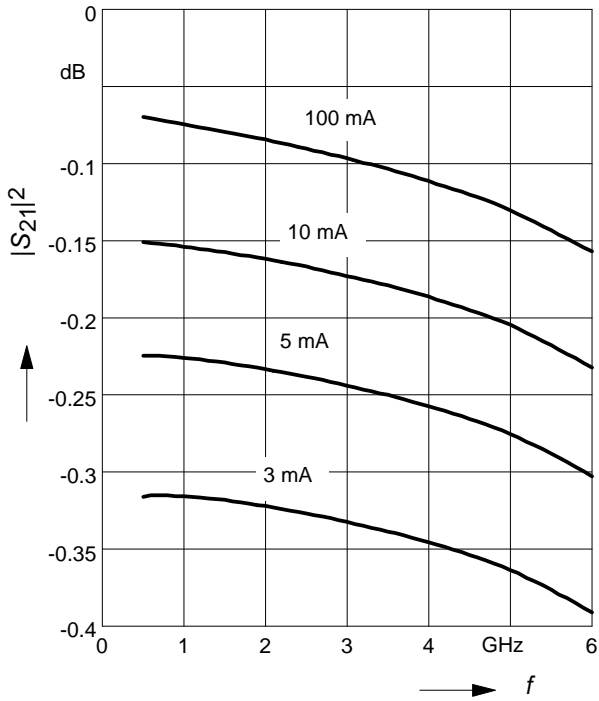
BAR64-04W, BAR64-06W



Insertion loss $|S_{21}|^2 = f(f)$

I_F = Parameter

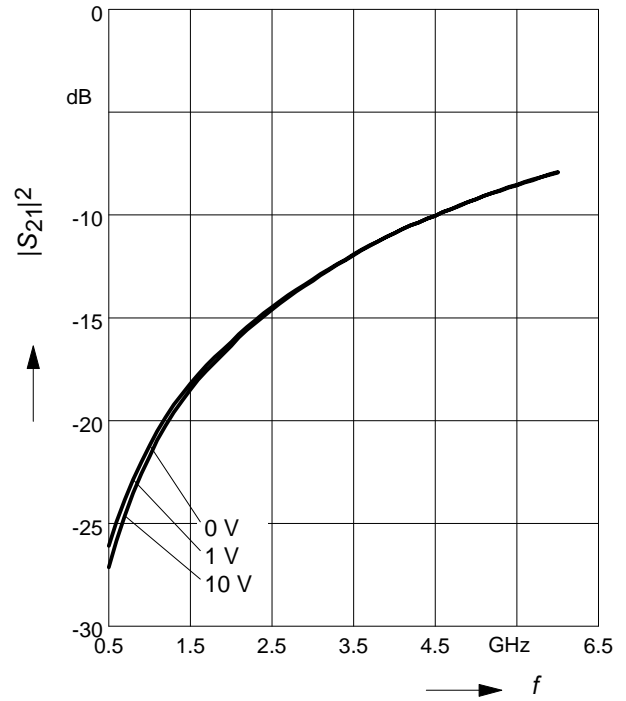
BAR64-02L in series configuration, $Z = 50\Omega$



Isolation $|S_{21}|^2 = f(f)$

V_R = Parameter

BAR64-02L in series configuration, $Z = 50\Omega$



**Published by Infineon Technologies AG,
St.-Martin-Strasse 53,
81669 München**

**© Infineon Technologies AG 2004.
All Rights Reserved.**

Attention please!

The information herein is given to describe certain components and shall not be considered as a guarantee of characteristics.

Terms of delivery and rights to technical change reserved.

We hereby disclaim any and all warranties, including but not limited to warranties of non-infringement, regarding circuits, descriptions and charts stated herein.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.